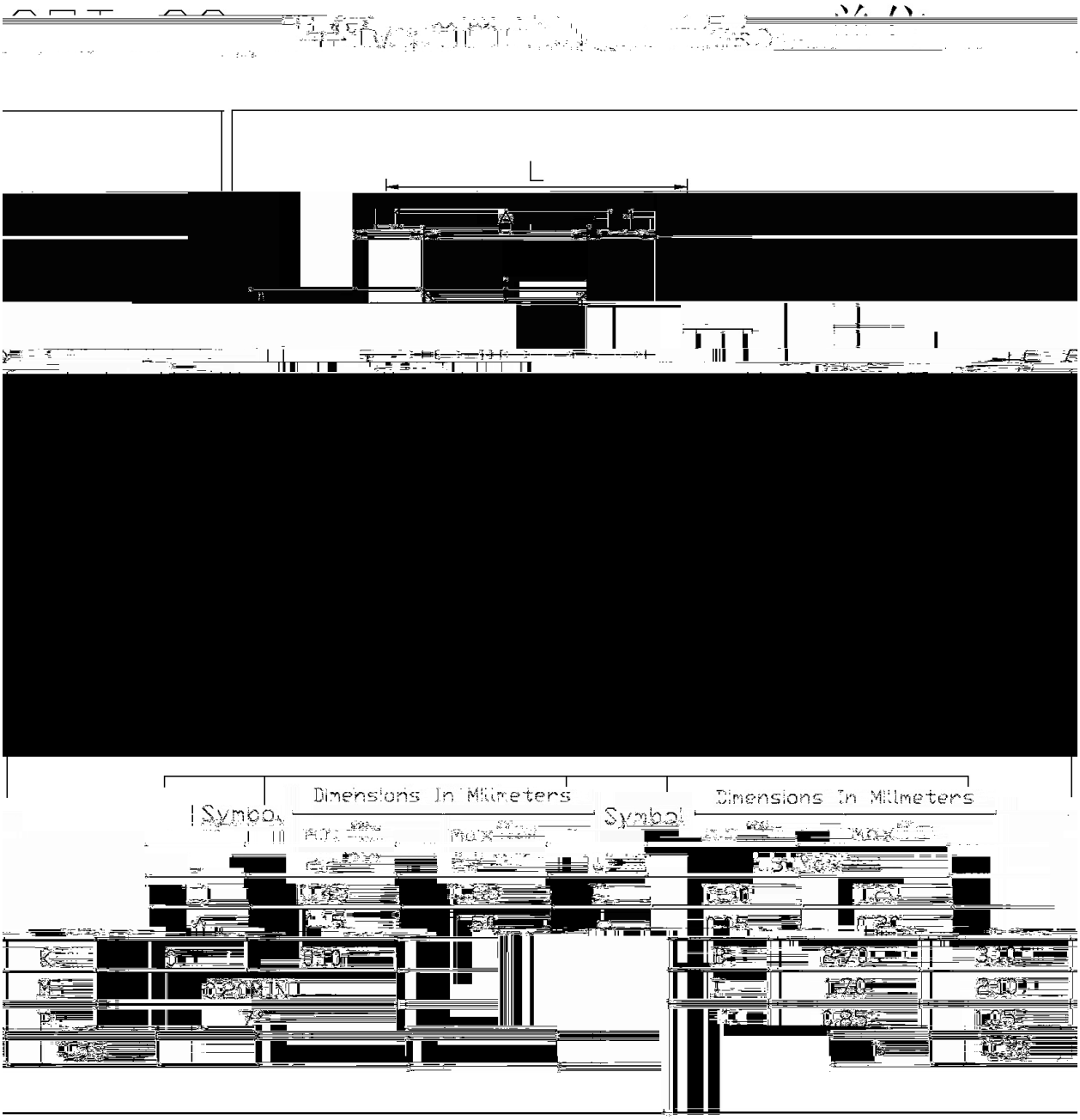
	! " #	$! % & '	! ( ) % * +	, -	. /
			0 1 2 3 4 5 6 7 8	9 : ;	< = >
			?@4 4 A 0 1) B C 3 4 D E 7 8 F G H I J K L M N O P Q R S T U D E B C % V W Q R X Y Z [\ A] ^ _ ` A a b c d \ e f \ g ] ^ _ ` A a b c d \ h	i j	< = >

SOT-23 NPN Silicon NPN transistor in a SOT-23

Parameter	Symbol

/ Package Dimensions



( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)

Note:

1	150	200	60	120sec;	1.Preheating:150~200℃, Time:60~120sec.
2	255±5			5±0.5sec;	2.Peak Temp.:255±5℃, Duration:5±0.5sec.
3		2	10℃/sec.		3. Cooling Speed: 2~10℃/sec.

/ Resistance to Soldering Heat Test Conditions

260±5℃	10±1 sec.	Temp.:260±5	Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm^3)		
	Units/Reel /	Reels/Inner Box /	Units/Inner Box /	Inner Boxes/Outer Box	Units/Outer Box			
SOT-23	3,000	10	30,000	6	180,000	7″ ×8	180×120×180	390×385×205